V1 — 06/26

Qualitek 818 No Clean Leaded Solder Paste Sn62/Pb36/Ag2

SKU: 390-818 | Sizes: Sn62/Pb36/Ag2 - 500gm JAR, Sn62/Pb36/Ag2 - 500gm CART

Features & Benefits

- **Alloy composition**: 62% Tin, 36% Lead, 2% Silver (Sn62/Pb36/Ag2)
- **Low residue**: Transparent, non-corrosive, and non-conductive post-soldering residues
- **Excellent activity** and **long stencil life** for efficient use
- **Type 3 particle size** (25-45µm) for precise soldering
- **Prints up to 8 per second** for high-speed applications
- **24-hour stencil life** and **48-hour tack time** for long-lasting performance
- **Excellent wetting** on OSP (Organic Solderability Preservative) surfaces
- **Air or nitrogen reflow** compatibility for versatile soldering
- **Available in 500g pots or semco carts**
- **Bellcore compliant** for high industry standards
- Featuring a tin (62%), lead (36%), and silver (2%) alloy, this paste delivers superb activity, long stencil life, and extended tack time, making it ideal for fast, efficient soldering

About the Qualitek 818 No Clean Leaded Solder Paste Sn62/Pb36/Ag2

Qualitek 818 No Clean Leaded Solder Paste (Sn62/Pb36/Ag2) is a high-quality, low-residue solder paste that ensures excellent performance in a variety of applications.
Featuring a tin (62%), lead (36%), and silver (2%) alloy, this paste delivers superb activity, long stencil life, and extended tack time, making it ideal for fast, efficient soldering.
The transparent, non-corrosive, and non-conductive post-soldering residues leave a clean finish. With a paste particle size of Type 3 (25-45µm), it offers excellent wetting on OSP and can be used with both air or nitrogen reflow processes.
The paste is **available in a 500g pot or semco cart**, and is Bellcore compliant for industry standards.

Specifications

Property	Detail
Application	ESD-protected areas, electronics mfg, cleanrooms